

2-1. CDMA & GPS General Specification

ITEM	CDMA	GPS
Tx Freq. range	824.04~848.97MHz	-
Rx Freq. range	869.04~893.97MHz	1575.42MHz
Channel Bandwidth	1.23MHz	2MHz
Channel Spacing	30KHz	Not Used
Number of Channel	832	1
Duplex Separation	45MHz	-
In/Output Impedance	50Ohm	50Ohm
Tx Local Frequency	F _{Tx} * 1.6666	-
Rx Local Frequency	F _{Rx} * 2	F _{Rx} * 2
TCXO Frequency	19.2MHz	19.2MHz
Freq. Stability	(FRX-45MHz)±300Hz	-
Operating Temperature	-30℃ ~ +60℃	-30℃ ~+60℃



lte	em	GSM 850	EGSM 900	DCS1800	PCS1900
Freq. Ba Uplink/D	nd[MHz] Downlink	824~849 869~894	880~915 925~960	1710~1785 1805~1880	1850~1910 1930~1990
ARFCN	l range	128~251	0~124 & 975~1023	512~885	512~810
Tx/Rx s	spacing	45MHz	45MHz	95MHz	80MHz
Mod. E Bit P		270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us
Time Slo Frame		576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms
Modulation	GSM/ GPRS	0.3GMSK	0.3GMSK	0.3GMSK	0.3GMSK
MS P	ower	33dBm ~5dBm	33dBm ~5dBm	30dBm ~0dBm	30dBm ~0dBm
Power	Class	5pcl ~ 19pcl	5pcl ~ 19pcl	Opcl ~ 15pcl	0pcl ~ 15pcl
Sens	itivity	-102dBm	-102dBm	-100dBm	-100dBm
TDMA	\ Mux	8	8	8	8
Cell Radius		35Km	35Km	2Km	2Km



2-2. GSM Tx Power Class

TX Power control level	GSM850	TX Power control level	EGSM900	TX Power control level	DCS1800	TX Power control level	PCS1900
5	33±2 dBm	5	33±2 dBm	0	30±3 dBm	0	30±3 dBm
6	31±2 dBm	6	31±2 dBm	1	28±3 dBm	1	28±3 dBm
7	29±2 dBm	7	29±2 dBm	2	26±3 dBm	2	26±3 dBm
8	27±2 dBm	8	27±2 dBm	3	24±3 dBm	3	24±3 dBm
9	25±2 dBm	9	25±2 dBm	4	22±3 dBm	4	22±3 dBm
10	23±2 dBm	10	23±2 dBm	5	20±3 dBm	5	20±3 dBm
11	21±2 dBm	11	21±2 dBm	6	18±3 dBm	6	18±3 dBm
12	19±2 dBm	12	19±2 dBm	7	16±3 dBm	7	16±3 dBm
13	17±2 dBm	13	17±2 dBm	8	14±3 dBm	8	14±3 dBm
14	15±2 dBm	14	15±2 dBm	9	12±4 dBm	9	12±4 dBm
15	13±2 dBm	15	13±2 dBm	10	10±4 dBm	10	10±4 dBm
16	11±3 dBm	16	11±3 dBm	11	8±4 dBm	11	8±4 dBm
17	9±3 dBm	17	9±3 dBm	12	6±4 dBm	12	6±4 dBm
18	7±3 dBm	18	7±3 dBm	13	4±4 dBm	13	4±4 dBm
19	5±3 dBm	19	5±3 dBm	14	2±5 dBm	14	2±5 dBm
				15	0±5 dBm	15	0±5 dBm



2-3. WCDMA General Specification

	WCDMA2100	WCDMA1900	WCDMA850	WCDMA900
Freq. Band[MHz]	1922~1977	1852~1907	824~849	880~915
Uplink/Downlink	2112~2167	1932~1987	869~894	925~960
ADEON	UL: 9612~9888	UL: 9262~9538	UL: 4132~4233	UL: 2712~2863
ARFCN range	DL: 10562~10838	DL: 9662~9938	DL: 4357~4458	DL: 2937~3088
Tx/Rx spacing	190MHz	80MHz	45MHz	45MHz
Mod. Bit rate/ Bit Period	3.84 Mcps	3.84 Mcps	3.84 Mcps	3.84 Mcps
Time Slot Period/Frame	FrameLength:10ms	FrameLength:10ms	FrameLength:10ms	FrameLength:10ms
Period	Slotlength:0.667ms	Slotlength:0.667ms	Slotlength:0.667ms	Slotlength:0.667ms
Modulation	QPSK/HQPSK	QPSK/HQPSK	QPSK/HQPSK	QPSK/HQPSK
MS Power	24dBm~-50dBm	24dBm~-50dBm	24dBm~-50dBm	24dBm~-50dBm
Power Class	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)
Sensitivity	-106.7dBm	-106.7dBm	-106.7dBm	-106.7dBm
TDMA Mux	8	8	8	8
Cell Radius	2Km	2Km	2Km	2Km



2-4. TD-SCDMA General Specification

	Band34	Band39
Freq. Band[MHz] Uplink/Downlink	2010~2025	1880~1920
ARFCN range	10054~10121	9404~9596
Tx/Rx spacing	1	/
TCXO Frequency	19.2MHz	19.2MHz
Modulation	QPSK/16-QAM	QPSK/16-QAM
MS Power	-49dBm~ 25dBm	-49dBm~ 25dBm
Power Class	2 (max: 24 +1/-3dBm)	2 (max: 24 +1/-3dBm)
Sensitivity	-108dBm/1.28MHz	-108dBm/1.28MHz
Cell Radius	>10Km	>10Km
In/Output Impedance	50Ω	50Ω
Operating Temperature	-30℃ ~ +60℃	-30℃ ~ +60℃



2-5. LTE General Specification(FDD)

	Band1 (FDD)	Band3 (FDD)	Band5 (FDD)	Band7 (FDD)	Band8 (FDD)
Freq. Band[MHz] UL/DL	1920~1980 2110~2170	1710~1785 1805~1880	824~849 869~894	2500~2570 2620~2690	880~915 925~960
ARFCN range UL/DL Tx/Rx spacing	18000~18599 0~599 190MHz	19200~19949 1200~1949 95MHz	20400~20649 2400~2649 45MHz	20750~20449 2750~3449 120MHz	21450~21799 3450~3799 45MHz
TCXO Frequency	19.2MHz	19.2MHz	19.2MHz	19.2MHz	19.2MHz
Modulation	QPSK/16-QAM/64- QAM	QPSK/16-QAM/64- QAM	QPSK/16-QAM/64- QAM	QPSK/16-QAM/64- QAM	QPSK/16-QAM/64- QAM
MS Power	-40dBm~ 25dBm	-40dBm~ 25dBm	-40dBm~ 25dBm	-40dBm~ 25dBm	-40dBm~ 25dBm
Power Class	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)
Sensitivity	-100 (BW:5 MHz) -97 (BW:10 MHz) -95.2 (BW:15MHz) -94 (BW:20MHz)	-101.7 (BW:1.4MHz) -98.7(BW:3MHz) -97 (BW:5 MHz) -94 (BW:10 MHz) -92.2 (BW:15MHz) -91 (BW:20MHz)	- 105.7(BW:1.4MHz) -103.7(BW:3MHz) -102 (BW:5 MHz) -99 (BW:10 MHz)	-98 (BW:5 MHz) -95 (BW:10 MHz) -93.2 (BW:15MHz) -92 (BW:20MHz)	- 105.7(BW:1.4MHz) -103.7(BW:3MHz) -102 (BW:5 MHz) -99 (BW:10 MHz) -97 (BW:15MHz) -96 (BW:20MHz)
Cell Radius	>5Km	>5Km	>5Km	>5Km	>5Km
In/Output Impedance	50Ω	50Ω	50Ω	50Ω	50Ω
Operating Temperature	-30°C ~ +60°C	-30°C ~ +60°C	-30°C ~ +60°C	-30°C ~ +60°C	-30°C ~ +60°C



2-6. LTE General Specification(TDD)

	Band38 (TDD)	Band39 (TDD)	Band40 (TDD)	Band41 (TDD)
Freq. Band[MHz] Uplink/Downlink	2570~2620	1880~1920	2300~2400	2555~2655
ARFCN range	37750~38249	38250~38649	38650~39649	40240~41240
Tx/Rx spacing	/	/	/	/
TCXO Frequency	19.2MHz	19.2MHz	19.2MHz	19.2MHz
Modulation	QPSK/16-QAM/64-QAM	QPSK/16-QAM/64-QAM	QPSK/16-QAM/64-QAM	QPSK/16-QAM/64-QAM
MS Power	-40dBm~ 25dBm	-40dBm~ 25dBm	-40dBm~ 25dBm	-40dBm~ 25dBm
Power Class	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)
Sensitivity	-100 (BW:5 MHz) -97 (BW:10 MHz) -95.2 (BW:15MHz) -94 (BW:20MHz)	-100 (BW:5 MHz) -97 (BW:10 MHz) -95.2 (BW:15MHz) -94 (BW:20MHz)	-100 (BW:5 MHz) -97 (BW:10 MHz) -95.2 (BW:15MHz) -94 (BW:20MHz)	-99 (BW:5 MHz) -96 (BW:10 MHz) -94.2 (BW15MHz) -93 (BW:20MHz
Cell Radius	>5Km	>5Km	>5Km	>5Km
In/Output Impedance	50Ω	50Ω	50Ω	50Ω
Operating Temperature	-30℃ ~ +60℃	-30℃ ~ +60℃	-30℃ ~ +60℃	-30℃ ~ +60℃





Main Function

Item	Description
os	Android M OS
RF	GSM850/900/1800/1900, CDMA, WCDMA(1/2/5/8), TDS(34/39), FDD(1/3/5/7/8)TDD(38/39/40/41)
Battery	3000mAh
Base Band	MSM8953 OCTA A53 2.2GHz
Other RF	GPS, Glonass, Beidou, BT4.2, USB 2.0, WIFI 802.11 a/b/g/n, NFC
Camera	F : 16M FF F1.9 R : 16M PDAF F1.9 w/Dual LED Flash
LCD	5.2" super AMOLED, 1920*1080(FHD)
RAM	4GB
Sensor	Proxi+RGB / Accel / Gyro, Magnetic / FPS
Accessory	Charger: 5V/2A or 9V/1.67A Data cable: 2.8pi, 1.2m

9. Reference Abbreviate



Reference Abbreviate

— AAC: Advanced Audio Coding.— AVC: Advanced Video Coding.

- BER: Bit Error Rate

- BPSK: Binary Phase Shift Keying

- CA : Conditional Access

— CDM : Code Division Multiplexing

- C/I: Carrier to Interference

- DMB: Digital Multimedia Broadcasting

EN: European StandardES: Elementary Stream

- ETSI: European Telecommunications Standards Institute

- MPEG: Moving Picture Experts Group

- PN: Pseudo-random Noise

- PS: Pilot Symbol

- QPSK: Quadrature Phase Shift Keying

RS : Reed-SolomonSI : Service Information

- TDM: Time Division Multiplexing

- TS: Transport Stream

1. Safety Precautions



1-1. Repair Precaution

Before attempting any repair or detailed tuning, shield the device from RF noise or static electricity discharges.

Use only demagnetized tools that are specifically designed for small electronic repairs, as most electronic parts are sensitive to electromagnetic forces.

Use only high quality screwdrivers when servicing products. Low quality screwdrivers can easily damage the heads of screws.

Use only conductor wire of the properly gauge and insulation for low resistance, because of the low margin of error of most testing equipment.

We recommend 22-gauge twisted copper wire.

Hand-soldering is not recommended, because printed circuit boards (PCBs) can be easily damaged, even with relatively low heat. Never use a soldering iron with a power rating of more than 100 watts and use only lead-free solder with a melting point below 250°C (482°F).

Prior to disassembling the battery charger for repair, ensure that the AC power is disconnected. Always use the replacement parts that are registered in the SEC system. Third-party replacement parts may not function properly.

1. Safety Precautions



1-2. ESD(Electrostatically Sensitive Devices) Precaution

Many semiconductors and ESDs in electronic devices are particularly sensitive to static discharge and can be easily damaged by it. We recommend protecting these components with conductive anti-static bags when you store or transport them.

Always use an anti-static strap or wristband and remove electrostatic buildup or dissipate static electricity from your body before repairing ESDs.

Ensure that soldering irons have AC adapter with ground wires and that the ground wires are properly connected.

Use only desoldering tools with plastic tips to prevent static discharge.

Properly shield the work environment from accidental electrostatic discharge before opening packages containing ESDs.

The potential for static electricity discharge may be increased in low humidity environments, such as air-conditioned rooms. Increase the airflow to the working area to decrease the chance of accidental static electricity discharges.

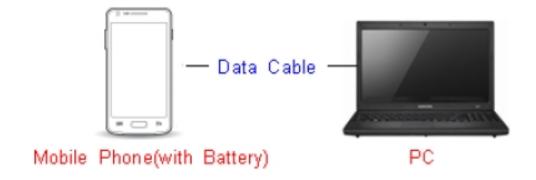


6-1. S/W installation

6-1-1. Required items in order to install S/W

- Installation program: Downloader Program (Odin3 v3.12.5.exe)
- Mobile Phone
- Data Cable
- Mobile device specific S/W: Binary files

X Settings



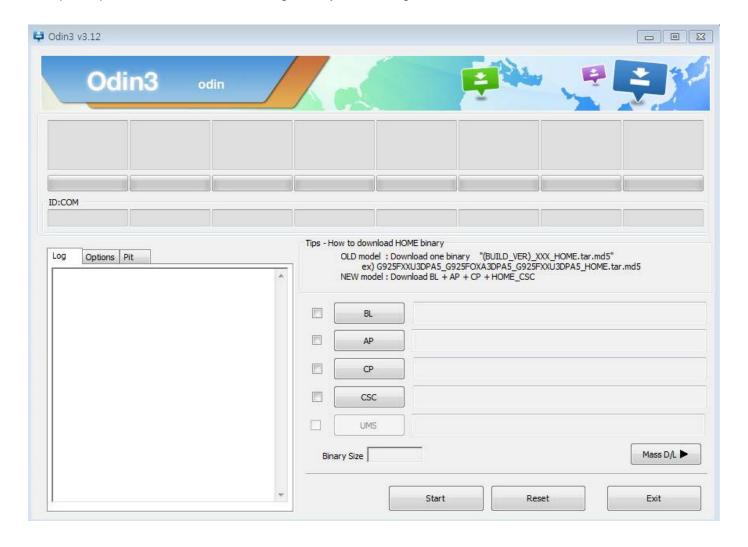


Data Cable: GH39-01886A



6-1-2. S/W Installation Program (Downloader program)

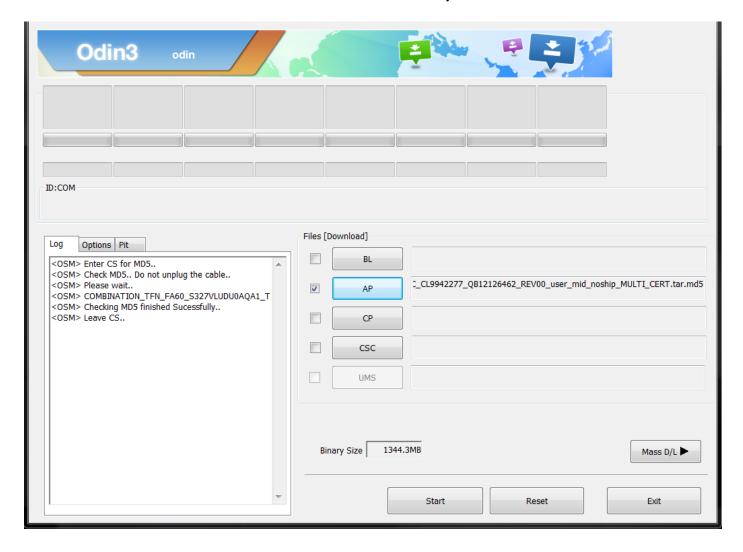
■ Open up the S/W Installation Program by executing the "Odin3 v3.12.5.exe"







- 1. Enable the check mark by click on the following options,
 - Check Auto Reboot, Re-Partition, and F. Reset Time-
 - Check PIT
 - Check Nand Erase All
 - Check BL, AP, CP, and CSC Files
 - * Note: "Odin v3.12 or above" checks MD5 checksum just after file selection.





2. Enter into Download Mode

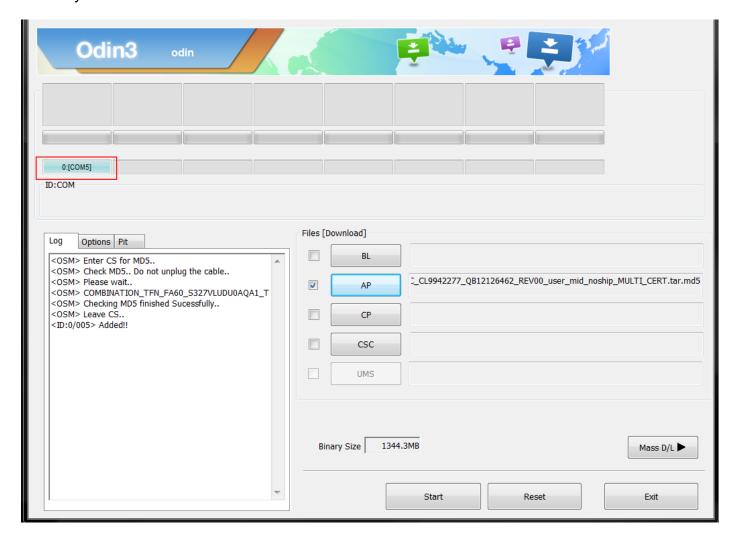
- Enter into Download Mode by pressing Home button, Volume Down button and Power On/Off Button simultaneously followed by pressing Volume up button as a direction of the phone.







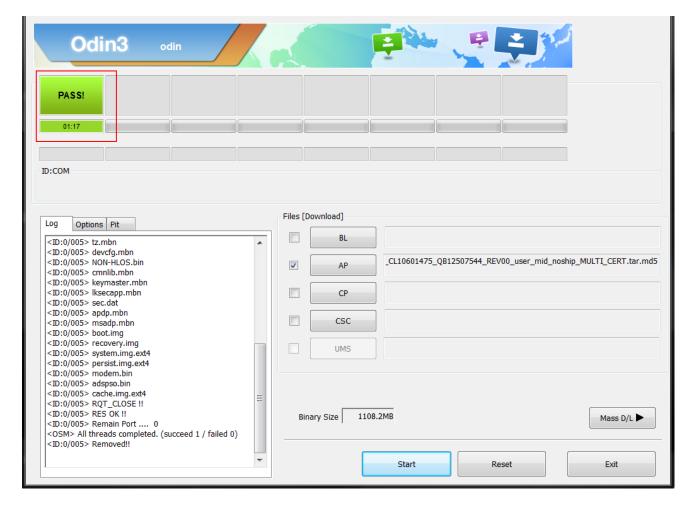
Connect the device to PC via Data Cable.
 Make sure that the one of communication ports [ID:COM] box is highlighted in sky blue. The device is now connected with the PC and ready to download the binary files in it.



6. Level 1 Repair



4. Start downloading the binary files into the device by clicking Start button on the screen. The green colored "PASS!" sign will appear on the upper-left box if the binary files have been successfully downloaded into the device.



- 5. Disconnect the device from the Data cable.
- Once the device boots up, you can check the version of the binary file or name by pressing the following code in sequence;
 *#1234#

You can perform Factory Reset by Settings → Accounts → Backup and reset

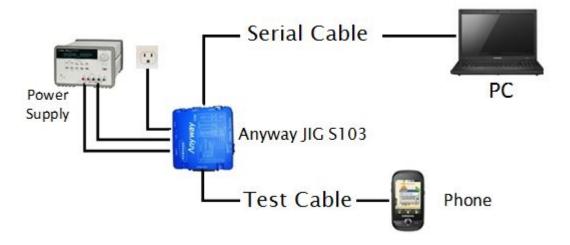


6-2 IMEI writing

6-2-1 Preparation

- New IMEI writing Program has been released.
- Supported Model: Models which CAB files are uploaded on HHPsvc INI File category, instead of ini file.
- Refer to below IMEI writing procedure.

- H/W

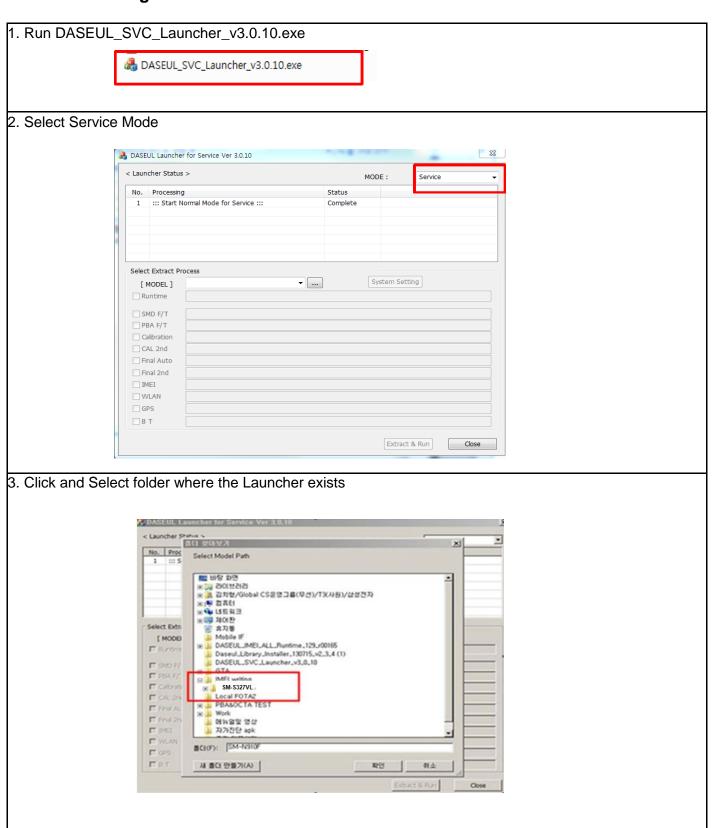


- S/W

① Library Install	To use Daseul, library files should be installed. Refer to SVC Bulletin "(11-82) Daseul (New IMEI writing Program) Library Install guide_rev1.0"
②Launcher	DASEUL_SVC_Launcher_v3_0_25 or higher -Uploaded on HHPsvc Notice
③ Runtime File	DASEUL_Runtime_Ver_3.1.139.0.CAB or higher -Uploaded on HHPsvc Notice Make 'ModelName' folder at the same position with launcher & Runtime file.
4Model File	Copy Model File under the 'Model Name' folder



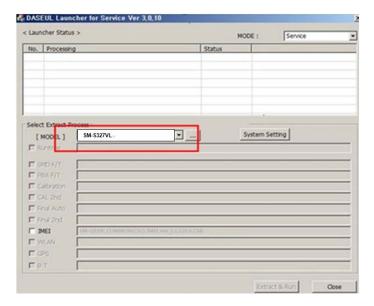
6-2-2 IMEI writing Process





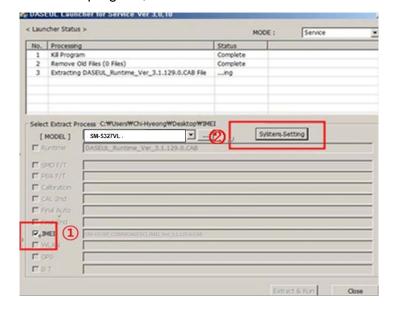


4. Select Model



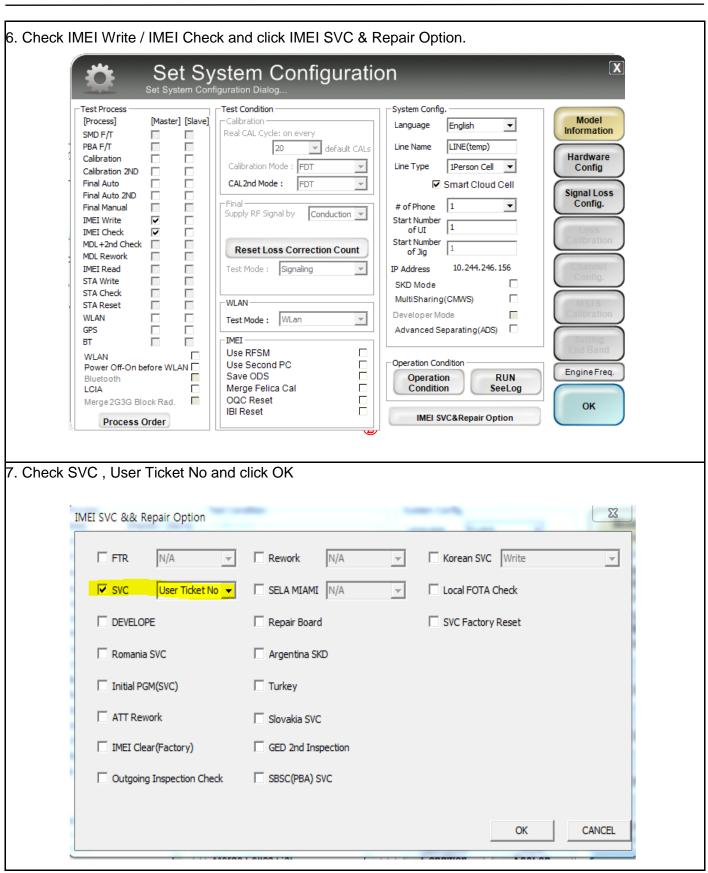
Check IMEI and click System Setting

※Once you setup the setting, you don't have to do it again, unless there is change. From second run of the IMEI program, check IMEI and click Extract & Run.





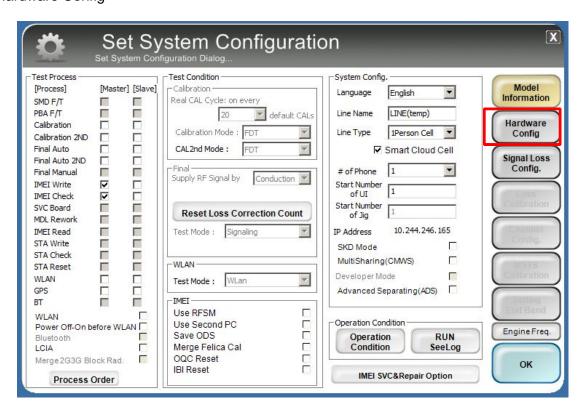




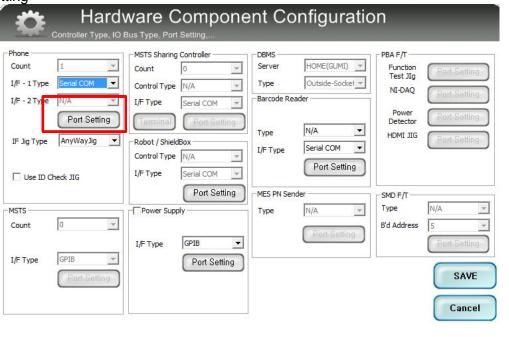




8. Click Hardware Config

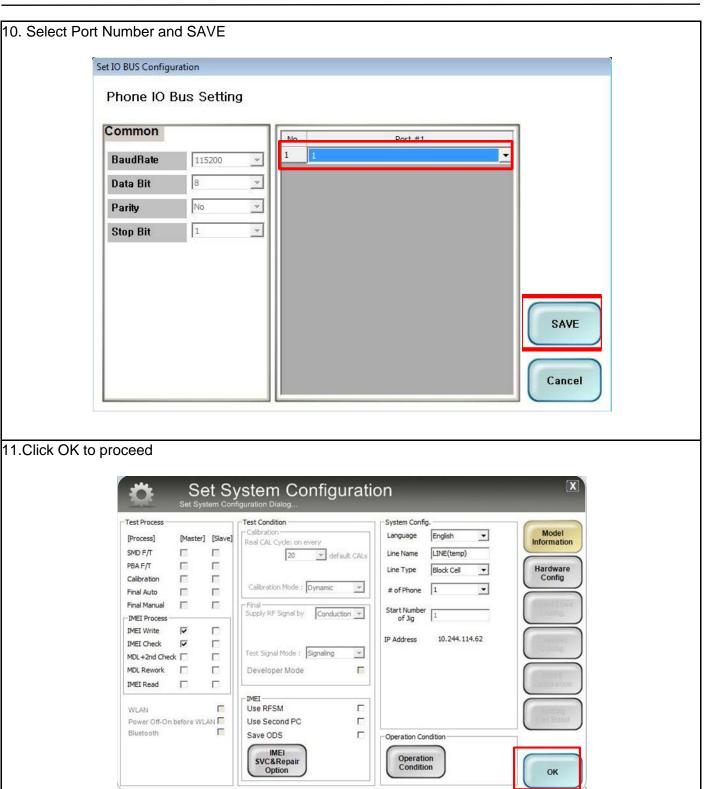


Click Port Setting



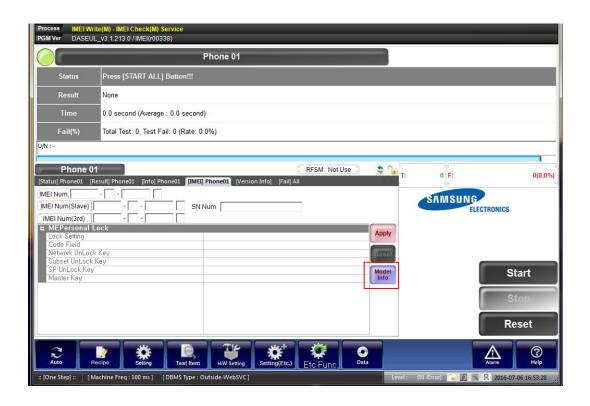








12. Click Model Info and OK when pop-up shows

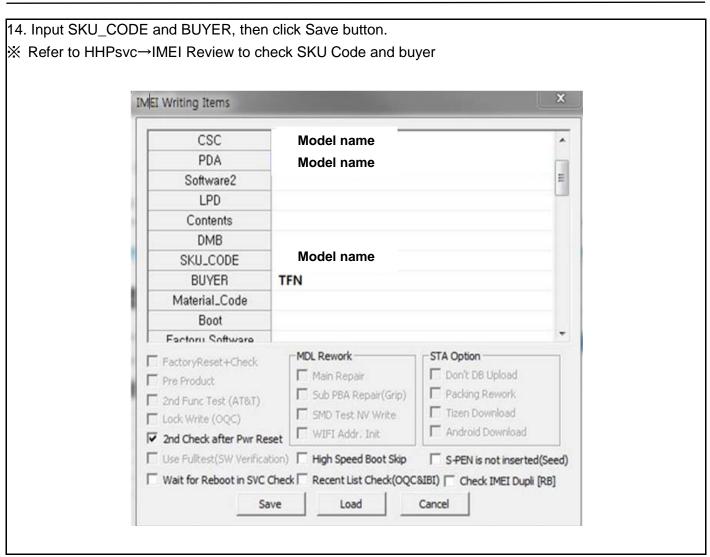


13. Click OK



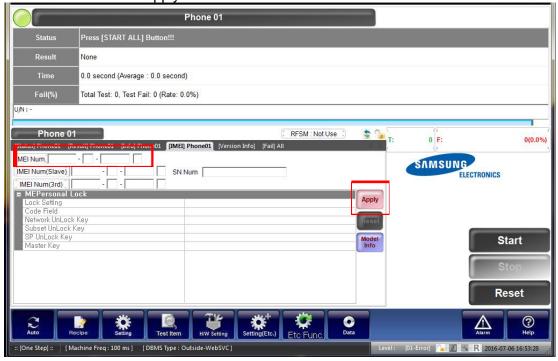




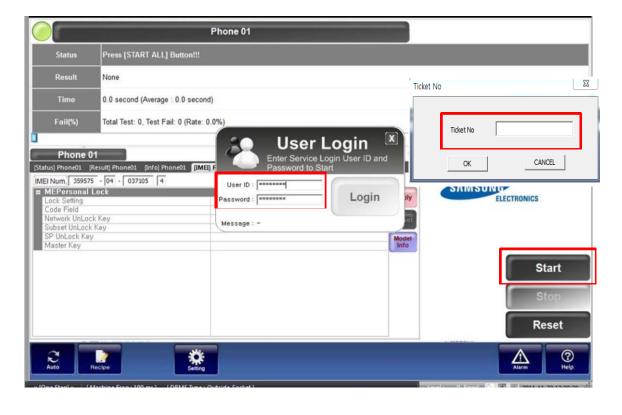




15. Input IMEI Number and click Apply



16. ① Click Start, and input IMEI writing ID and Password →②input Ticket No







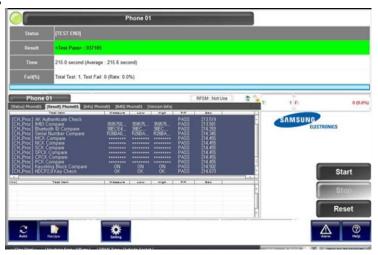
- 17. Connect the phone to Anyway JIG
- ※ When you connect the phone, the phone should be turned off.

After connecting the phone, the phone will be booted automatically.

18. IMEI Writing Proceeding



19. IMEI Writing Success





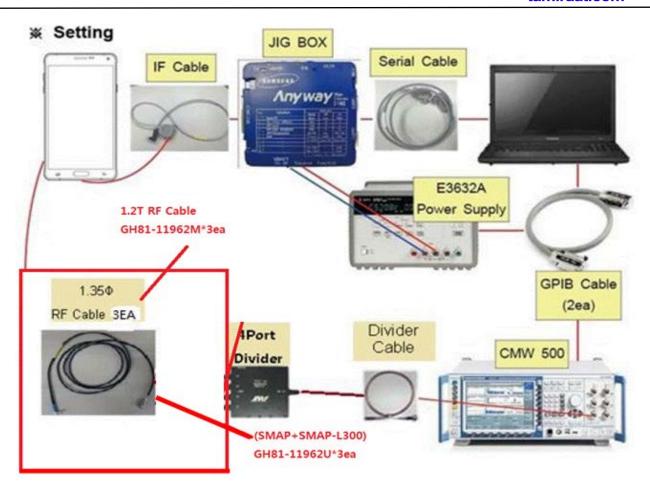
6-3 RF Calibration

6-3-1. Required items in order to calibrate RF

- Installation program: RF Calibration Program
- Daseul_Launcher_vx.x.xx.exe
- Daseul_CAL_ALL_Runtime_x.x.xxx.x.CAB
- Model File
- : Slave: SM-C5010_OPEN_CALIBRATION_Ver_3.1.268.2TJ03_S
- : Master: SM-C5010_OPEN_CALIBRATION_Ver_3.1.268.2TJ03_M
- * It is required to use the latest program.
- SM-C5010 Mobile Phone
- R&S CMW500
- E3632A Power Supply
- GPIB Cable (2ea)
- JIG BOX (Anyway S103)
- IF Cable (GH81-11962W)
- Adapter (GH81-11888K)
- UART Serial Cable
- RF Cable (GH81-11962U) 3EA
- 1.35ΦRF Cable (GH81-11962M 3ea)
- Divider Cable (GH81-11962B 1EA)

Table of test cables

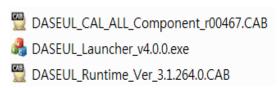
	GH81-11962W			
IF Cable	USB C type			
	GH81-11962M	GH81-11962U		
RF Cable (Manual)	1.2T, 102mm 3ea	SMAP, 300mm 3ea SWAP SWAP		
	GH81-11962A	GH81-11962B	GH81-11962E	
4 Port Divider	Divider 1ea	Divider Cable 1ea	50Ω terminator 1ea	



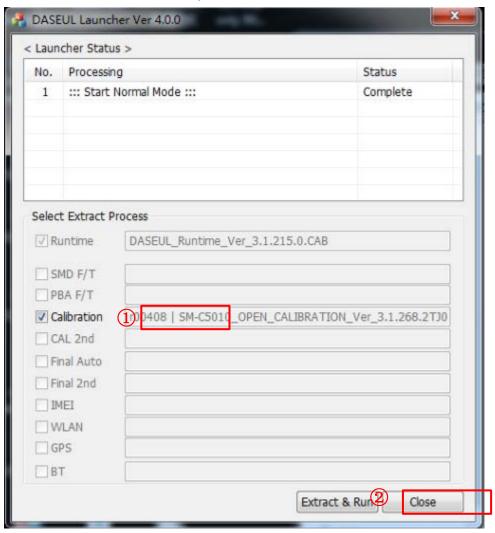


6-3-2. RF Calibration Program

1. Run the RF Calibration Program Launcher, 'DASEUL_Launcher_vx.x.xx.exe'.



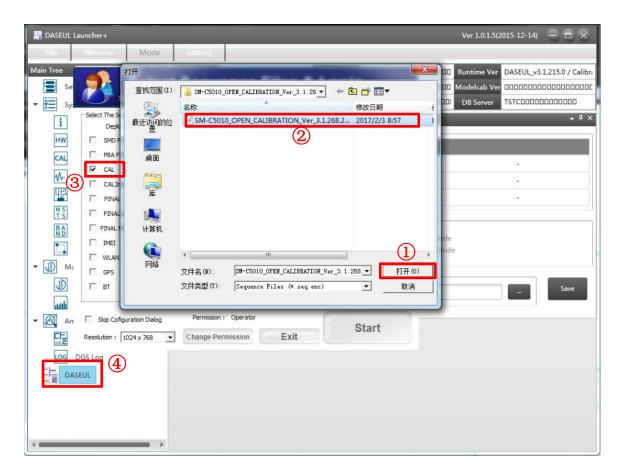
2. Check the 'Calibration' option and Click 'Extract & Run'.







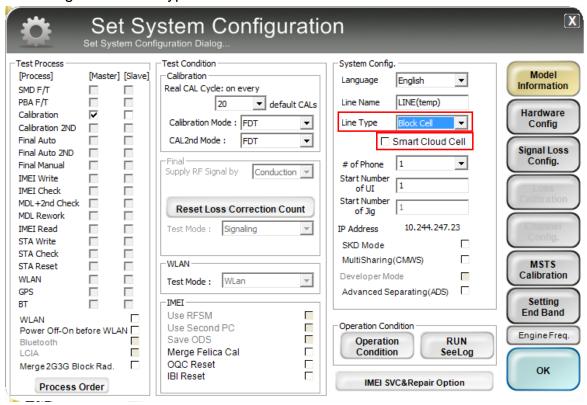
3. Check the 'CAL' and open the model file, then select 'Start' button. [SM-C5010]



6. Level 1 Repair



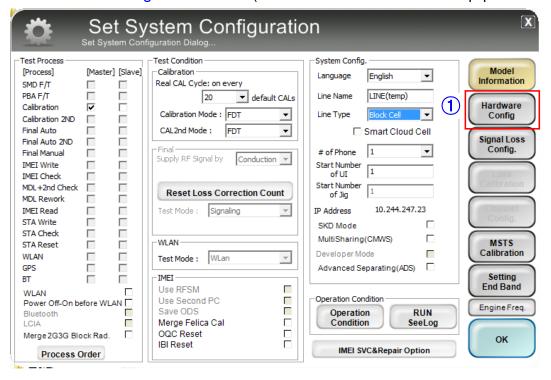
4. Change the Line Type to 'Block Cell' and disable 'Smart Cloud Cell'.

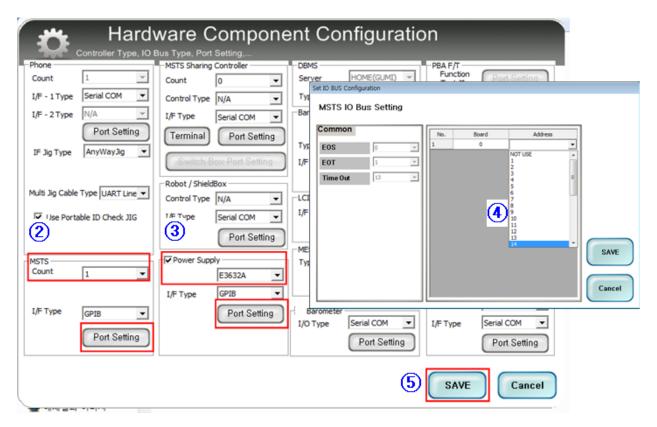






 Set the GPIB address of MSTS(CMW500) and Power Supply(E3632A) to enter 'Hardware Config' and 'Save'. (Check the GPIB address of equipments in advance)





6. Level 1 Repair



6. Press 'OK' to start RF Calibration after completing all settings.

